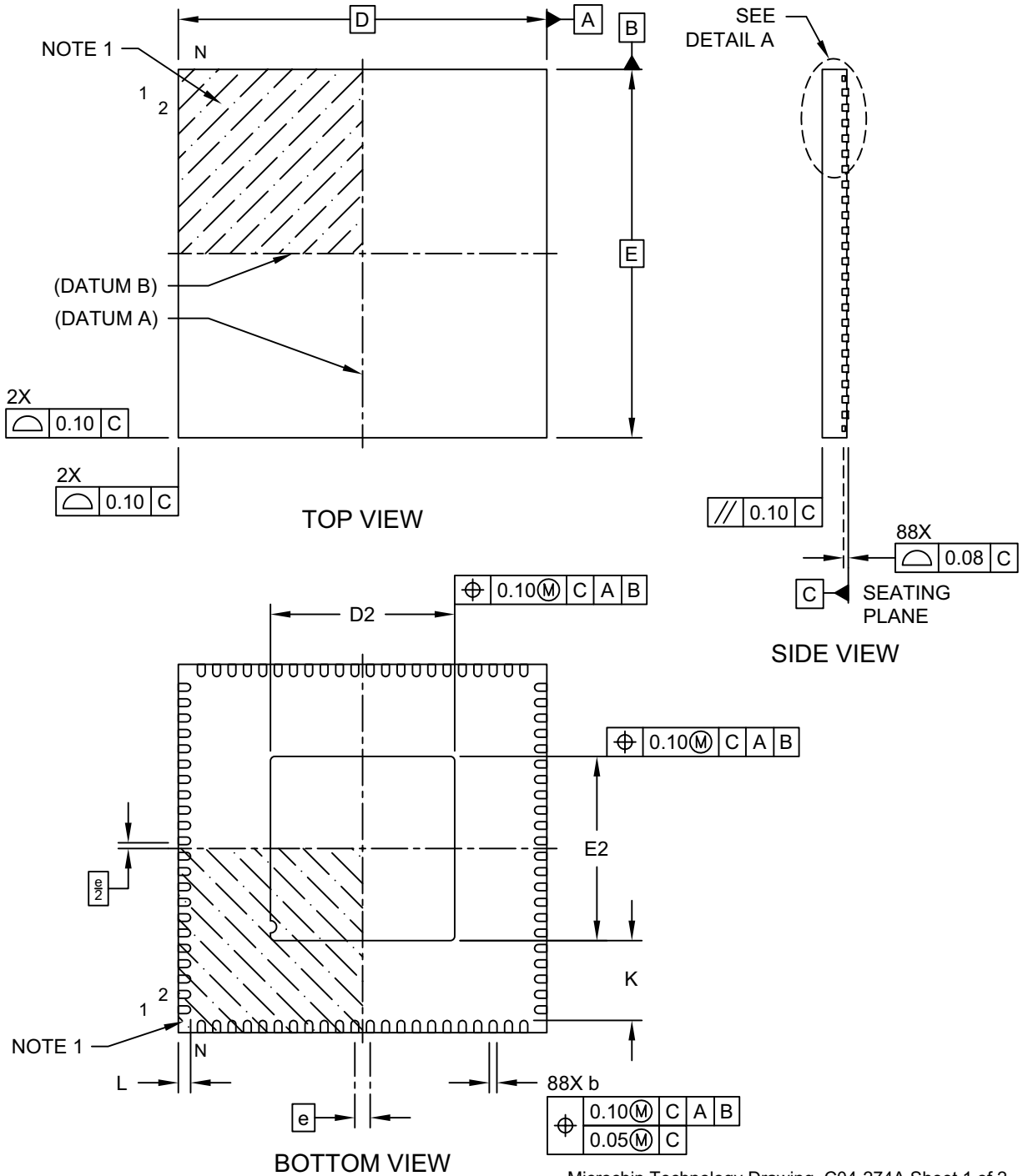


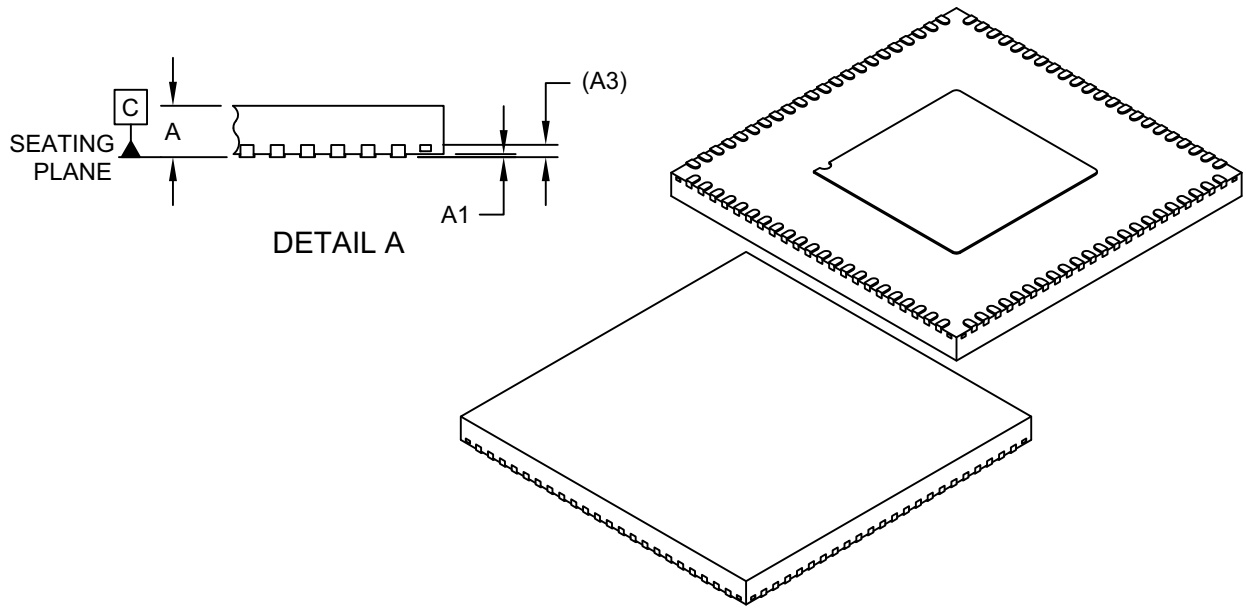
88-Lead Very Thin Plastic Quad Flat, No Lead Package (PJ) - 12x12 mm Body [VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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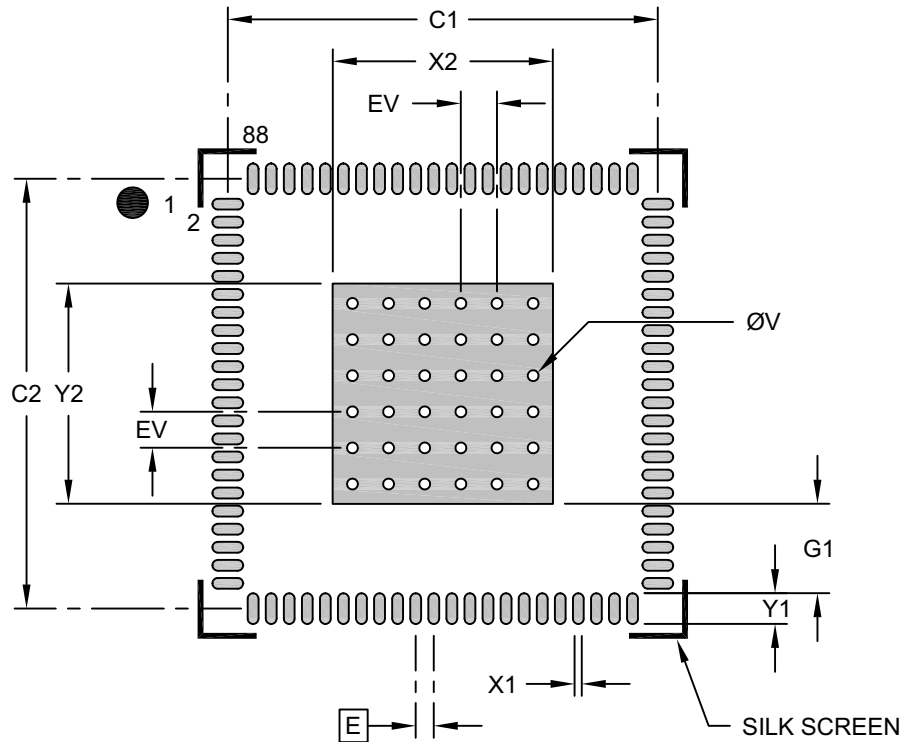
| Dimension Limits | Units | MILLIMETERS | | |
|-------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Terminals | N | 88 | | |
| Pitch | e | 0.50 BSC | | |
| Overall Height | A | 0.80 | 0.85 | 0.90 |
| Standoff | A1 | 0.00 | 0.02 | 0.05 |
| Terminal Thickness | A3 | 0.203 REF | | |
| Overall Length | D | 12.00 BSC | | |
| Exposed Pad Length | D2 | 5.90 | 6.00 | 6.10 |
| Overall Width | E | 12.00 BSC | | |
| Exposed Pad Width | E2 | 5.90 | 6.00 | 6.10 |
| Terminal Width | b | 0.18 | 0.25 | 0.30 |
| Terminal Length | L | 0.30 | 0.40 | 0.50 |
| Terminal-to-Exposed-Pad | K | 2.50 | - | - |

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

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RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|---------------------------------|-------|-------------|-------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.50 BSC | | |
| Optional Center Pad Width | X2 | | | 6.10 |
| Optional Center Pad Length | Y2 | | | 6.10 |
| Contact Pad Spacing | C1 | | 11.90 | |
| Contact Pad Spacing | C2 | | 11.90 | |
| Contact Pad Width (X88) | X1 | | | 0.30 |
| Contact Pad Length (X88) | Y1 | | | 0.85 |
| Contact Pad to Center Pad (X88) | G1 | 0.20 | | |
| Thermal Via Diameter | V | | 0.30 | |
| Thermal Via Pitch | EV | | 1.00 | |

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2274A